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Adam G. Gildea, Justin C. Long, Eric Eisenbraun, College of Nanoscale Science and Engineering, The University at Albany; Vincent Omarjee, Nathan Stafford, François Doniat, Christian Dussarrat, American Air Liquide

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Andrew Stamper, IBM Corporation; Gangadharan Sivaraman, Ravi Sankar, KLA-Tencor

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Sheng-Yuan Chang, Yu-Chung Chen, An Chyi Wei, Hong-Ji Lee, Nan-Tzu Lian, Tahone Yang, Kuang-Chao Chen, Chih-Yuan Lu, Macronix International Co., Ltd.

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Ikhoon Shin, Jason Doub, Keith Mortesen, Raymond Lappan, ON Semiconductor

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Michael E. Lombardi, Intel Corp

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Mohammad Kazemi, Helmuth Treichel, Rito Ligutom, Xyratex International

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Thongchai Thongvigitmanee, Wisut Titiroongruang, King Mongkut's Institute of Technology Ladkrabang; Archkom Srihapat, Amporn Poyai, Thai Microelectronics Center

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Ariane Ferreira, Agnés Roussy, Christelle Kernaflen; Ecole Nationale Supérieure des Mines de Saint-Etienne; Dietmar Gleispach, Günter Hayderer, austriamicrosystems AG; Hervé Gris, Jérôme Besnard, PDF Solutions

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Agnés Roussy, M. Gedion,, EMSE-CMP; N. Crousier, J. Pinaton K. Labory, STMicroelectronics

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Matthias Thomas Bostelmann, ALTIS Semiconductor

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Zubin Mevawalla, Gary S. May, Georgia Institute of Technology; M. Honjo, M.W. Kiehlbauch, Micron Technology

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Weihua Tong, K. Suresh, Miowchin Tan, Peter Benyon, Vish Srinivasan, Jinping Liu, GLOBALFOUNDRIES

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Kevin Boyd, IBM Semiconductor Research and Development Center; Adam Monkowski, Jialing Chen, Tao Ding, Joseph Monkowski, Pivotal Systems

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Paul Brabant, Keith Chung, Manabu Shiniriki, Scott Hasaka, Dane Scott, Mark Wirzbibki, Terry Francis, MathesonGas; Hong He, Devendra K. Sadana, IBM Research at Albany NanoTechnology Center

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Steven J. Holmes, Yunpeng Yin, Chiew-seng Koay, Shyng-Tsong Chen, Karen Petrillo, Guillaume Landie, Scott Halle; Sean Burns, John C. Arnold, Terry Spooner, Matthew Colburn, Rex Chen, S. Liu, R. Varanasi, IBM; Cherry Tang, Nicolette Fender, Brian Osborn, Lovejeet Singh, Mark Slezak, JSR Micro; Sumanth Kini, KLA-Tencor; Hideyuki, Tomizawa, Toshiba; Shannon Dunn, Jason Cantone, David Hetzer, Shinichiro Kawakami, Tokyo Electron Technology

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Jasper Paul Munson, Jay Brown, Nikon Precision

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David Hanny, Applied Materials

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Hamid Khorram, Nikon Precision

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Gunther Reinhart, Michael Heinz, Johannes Stock, Technische Universität München; Josef Zimmerman, Michael Schilp, Adolf Zitzmann, Jens Hellwig, Zimmermann & Schilp Handhabungstechnik GmbH

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Oliver Patterson, Andrew Stamper, IBM Semiconductor Research and Development Center; Roland Hahn, KLA-Tencor

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Gottfried Schmid, Infineon Technologies AG; Tilmann Hanitzsch, Senior Management Consultant

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Henry Antonovich, IBM Microelectronics

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Ray Fontaine, Chipworks, Inc.

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Brian L. Walsh, John Colt, Jr., Daniel Poindexter, Thomas Joseph, IBM Systems and

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Jeanne Paulette Bickford, Francis Chan, Mark Styduhar, Lee Wang, Robert Arelt, Ioanoa Graur, Steven Parker, Deborah Ryan, Tina Wagner, IBM Systems and Technology Group; Anand Kumaraswamy, IBM Corporation